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(54) METHOD FOR MAKING A THREE DIMENSIONAL INTEGRATED ELECTRONIC CIRCUIT

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(57) **ABSTRACT**

A method for making a three-dimensional integrated electronic circuit comprising steps for:

making a first electrically conductive portion on a first dielectric layer covering a first semiconductor layer; then

making a second dielectric layer covering the first electrically conductive portion such that the first electrically conductive portion is arranged between the first and second dielectric layers, and a second semiconductor layer arranged on the second dielectric layer; then

making a first electronic component in the second semiconductor layer, and a second electronic component in the first semiconductor layer; then

making an electrical interconnection electrically linking the first and second electronic components together, of which a first part passes through the first dielectric layer and electrically connects the second electronic component to the first electrically conductive portion and of which a second part passes through a part of the second dielectric layer and electrically connects the first electronic component to the first electrically conductive portion.